



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-07-14
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
DALC208SC6	8BWB*DAXLC08	A	Z8GA	2016-07-14
Amount		UoM	Unit type	ST ECOPACK Grade
14.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2.9X1.625X1.175	4	gull wing	
Comment	Package: SOT 23 - 6L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	88WB*DAXLC08					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.229	mg	supplier	die	Silicon (Si)	7440-21-3		0.153	mg	668122	10929
				supplier	metallization	Aluminium (Al)	7429-90-5		0.070	mg	305677	5000
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	26201	429
Leadframe	Copper & its alloys	6.535	mg	supplier	Alloy	Copper(CU)	7440-50-8		6.213	mg	950727	443786
				supplier	Alloy	Iron(Fe)	7439-89-6		0.150	mg	22953	10714
				supplier	Alloy	Phosphorus (P)	12185-10-3		0.005	mg	765	357
				supplier	Alloy	Zinc(Zn)	7440-66-6		0.008	mg	1224	571
				supplier	Coating	Silver(Ag)	7440-22-4		0.159	mg	24331	11357
Die attach	Other Organic Materials	0.047	mg	supplier	Glue	Silver(Ag)	7440-22-4		0.035	mg	744681	2500
				supplier	Glue	Acrylate monomer	Proprietary		0.007	mg	148936	500
				supplier	Glue	Heterocyclic organic compound	Proprietary		0.004	mg	85106	286
				supplier	Glue	Treated silica	Proprietary		0.001	mg	21277	71
Bonding	Other inorganic materials	0.034	mg	supplier	Bonding wire	Copper(CU)	7440-50-8		0.034	mg	1000000	2429
Encapsulation	Other Organic Materials	6.948	mg	supplier	Molding compound	Silica Fused	60676-86-0		6.023	mg	866868	430214
				supplier	Molding compound	Epoxy Resin	25068-38-6		0.556	mg	80023	39714
				supplier	Molding compound	Phenol Resin	29690-82-2		0.347	mg	49942	24786
				supplier	Molding compound	Carbon Black	1333-86-4		0.022	mg	3167	1571
Finishing	Other inorganic materials	0.207	mg	supplier	Connections coating	Tin(Sn)	7440-31-5		0.207	mg	1000000	14786